

Packaging & Delivery

Packaging Details

Retail package: bottle

Delivery Time

3~5 days, exact time depends on quantity

BEST-705 Lead-free brand silver tin lead solder paste

product description

BEST-solder (Tin) paste is the best choice of reballing IC .

original BEST brand ,

Quality Verified

Application: can be used for laptop /computer/mobile phone/home Appliances SMD IC and BGA IC repairing ,tools for chip-levelrepairing and Electronics Manufacture line.

Technology Parameter

Model

BEST-705

Alloy composition:

Tin:99% / silver: 0.3% / copper:0.7%

Melting point :

226-229 °C

Tin powder particle size:

25-45/μm

Tin powder shapes:

spherical

Metal content:

89.5 ± 1%

Refrigeration temperature:

5 ~ 10 °C

N.W.:

50g/pc

What we can provide you with?

This product is produced for mobile phone repairing including 9 different types.

You can buy them separate, or can buy them 5pcs per set.You can make any combination of these 9 types for one set for your order.

Why choose us?

1.With 16 years experience in this field, we have the ability to provide good service and products in low cost

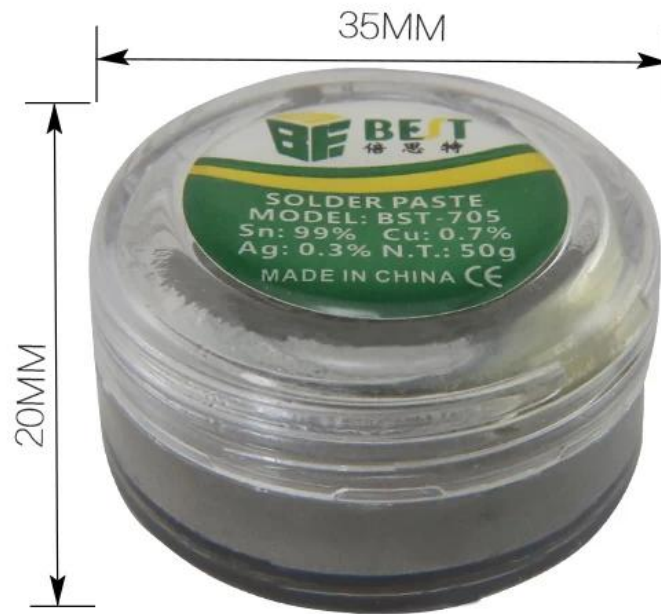
2.Adequate inventory assures enough products supplyment to our clients in a short period.

Product show

PRODUCT DISPLAY



PRODUCT DETAILS



Name: Solder paste

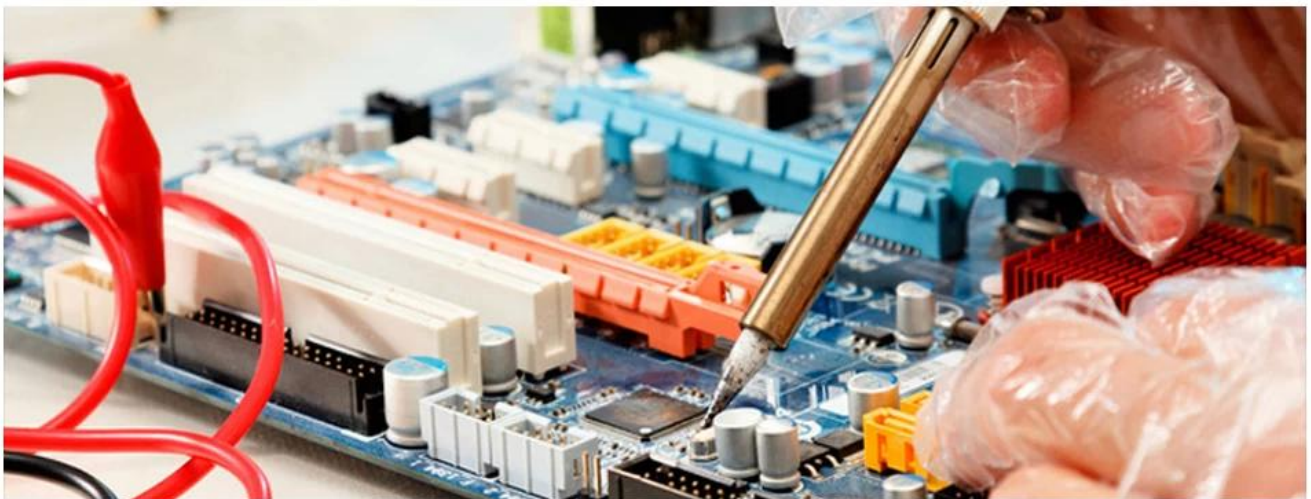
Model: BST-705

Size: $\phi 35 \times 20$ mm

Weight: 40g

Composition: SN99/AG0.3/CU0.7

Melting point: 226°C~229°C





Storage: Chilled in refrigerator, the best refrigeration temperature is 5°C~10°C.

Features: 1. When continuous printing, its viscosity changes less, which can obtain very stable printing.

2. The circuit with the spacing of 0.4-0.6mm and above can complete fine printing.

3. With excellent weld ability, it can show proper viscosity in different parts.

4. It is suitable for the return welding furnace of general atmosphere and nitrogen.

5. Good weldability can be obtained at extremely high peak temperature.

PRODUCT PHOTOGRAPH





